

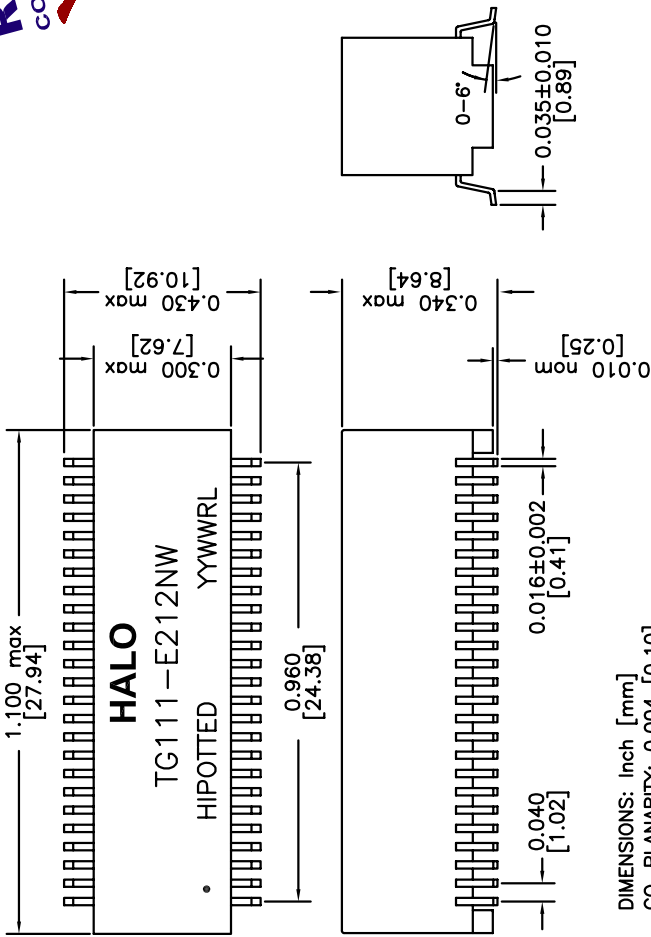


PART NO. : TG111-E212NWRL

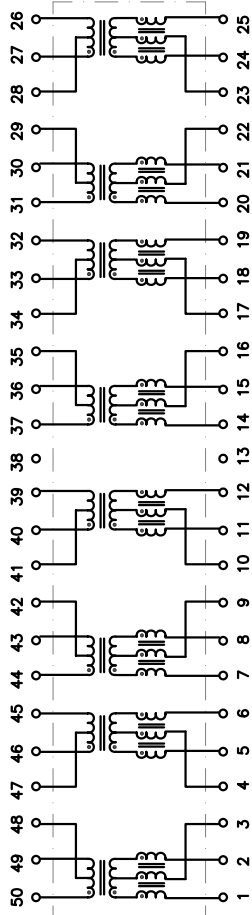
50PIN 0.040" LEAD PITCH SMT PACKAGE
DESIGNED FOR DUAL-PORT GIGABIT, IEEE802.3ab OR
FOUR-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS
COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH
350mA CURRENT CARRYING CAPACITY FOR PoE
RoHS COMPLIANT
COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STDP-020C
EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @ 25° C

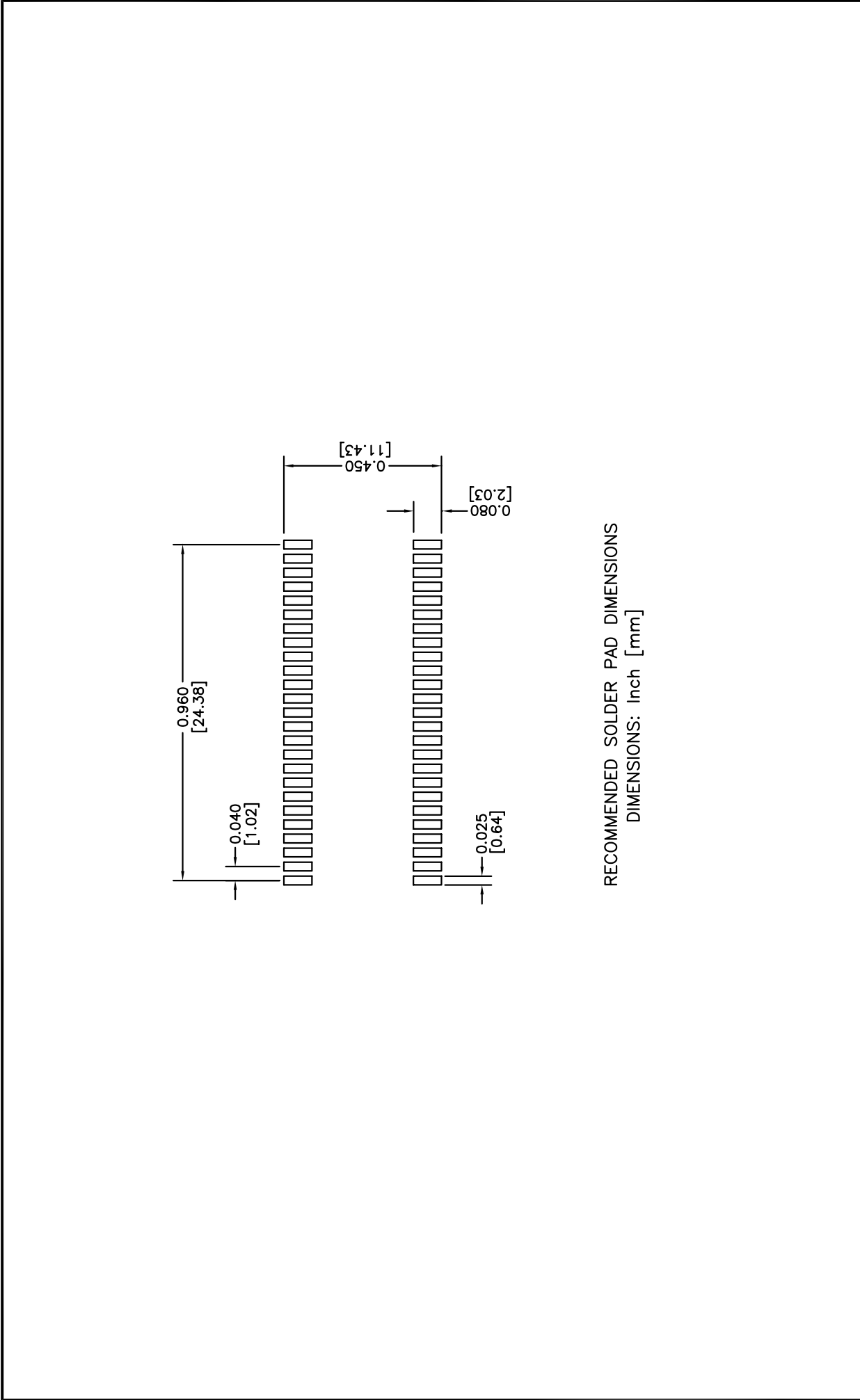
URNS RATIO	1CT:1CT±2%
OCL (100KHz,0.1Vrms,8mADC)	350µH min
INSERTION LOSS	-1.1dB max
RETURN LOSS	-18dB min
1-40MHz	-14dB min
60MHz	-12dB min
80MHz	-10dB min
100MHz	-40dB typ
CMR	-50dB typ
1-100MHz	-45dB typ
CROSSTALK	-40dB typ
1-30MHz	1,500Vrms
60MHz	
100MHz	
ISOLATION	



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL		ISOLATION MODULE		SIGNATURES		REV.		DESC.		DATE	
FOR		FAST/GIGABIT ETHERNET		DRAWN PETER LU		A		FIRST ISSUE		5/12/06	
PART NO. TG111-E212NWRL				CHECKED LEI KEONG		B		PROD. RELEASE		8/31/06	
SCALE NONE		PAGE 1 OF 2		APPROVED PETER LU		C		REV TOE LENGTH TOL.		3/20/08	
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE				FILE E212NWRL.DWG							



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE		TITLE		ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE	
		FOR		FAST/GIGABIT ETHERNET		DRAWN	PETER LU	5/12/06	A	FIRST ISSUE	5/12/06	
				PART NO. TG111-E212NWRL		CHECKED	LEI KEONG	3/20/08	B	PROD. RELEASE	8/31/06	
		SCALE		NONE	PAGE	2 OF 2	APPROVED	PETER LU	3/20/08	C	REV TOE LENGTH TOL.	3/20/08
						FILE		E212NWRL.DWG				